



12V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	Rds(on) max	I _D T _A = +25°C
	$10m\Omega$ @ $V_{GS} = 4.5V$	10.7A
12V	$12m\Omega @ V_{GS} = 2.5V$	9.8A
	$14m\Omega @ V_{GS} = 1.8V$	9.1A
	$18m\Omega @ V_{GS} = 1.5V$	8.0A
	41mΩ @ V _{GS} = 1.2V	5.3A

Description

This new generation MOSFET has been designed to minimize the onstate resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switch
- **DC-DC Converters**
- **Power Management Functions**

Features

- Low On-Resistance
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: TSOT26
- Case Material Molded Plastic. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Solderable per MIL-STD-202, Method 208 @3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)

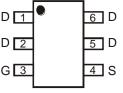




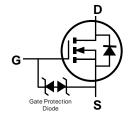
TSOT26



Top View



Top View Pin Configuration



Equivalent Circuit

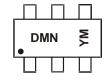
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN1019UVT-7	TSOT26	3,000/Tape & Reel
DMN1019UVT-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



DMN = Product Type Marking Code YM or YM = Date Code Marking Y or Y = Year (ex: C = 2015) M = Month (ex: 9 = September)

Date Code Kev

Year	2015		2016	2017		2018	2019	1	2020	2021		2022
Code	С		D	Е		F	G		Н	I		J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

DMN1019UVT Document number: DS37506 Rev. 2 - 2



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	12	V		
Gate-Source Voltage	V_{GSS}	±8	V		
Continuous Davis Compant (Nata 5) V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	10.7 8.6	А
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	12.7 10.1	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	70	Α		
Maximum Body Diode Forward Current (Note 5)	Is	2	Α		
Avalanche Current (Note 6) L = 0.1mH	I _{AS}	9.7	Α		
Avalanche Energy (Note 6) L =0.1mH	E _{AS}	4.7	mJ		

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	Б	1.73	W
Total Fower Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	1.11	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	<u> </u>	72.2	°C/W
Thermal Resistance, Junction to Ambient (Note 3)	t<10s	$R_{\theta JA}$	37.5	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	14.4	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

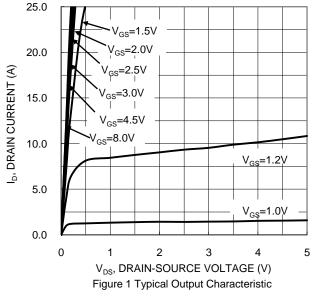
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

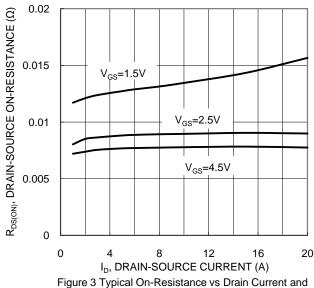
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	12	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	V _{DS} = 12V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	_	_	±2	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.35	0.53	8.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
		_	7	10		$V_{GS} = 4.5V, I_D = 9.7A$
		_	8	12		$V_{GS} = 2.5V, I_D = 9A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	10	14	mΩ	$V_{GS} = 1.8V, I_D = 8.1A$
		_	14	18		$V_{GS} = 1.5V, I_D = 4.5A$
		_	28	41		$V_{GS} = 1.2V, I_D = 2.4A$
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 10A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	2588	_	pF	101/11/101/
Output Capacitance	Coss	_	415	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1MHz
Reverse Transfer Capacitance	C _{rss}	_	394		pF	1 – 1101112
Gate Resistance	Rg	_	1.1		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 8V)	Qg	_	50.4	_		
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	28.0	_	nC	V _{DS} = 4V. I _D = 10A
Gate-Source Charge	Q _{gs}	_	3.2	_	IIC	V _{DS} = 4V, I _D = 10A
Gate-Drain Charge	Q_{gd}	_	5.6	_		
Turn-On Delay Time	t _{D(ON)}	_	4.7	_	ns	
Turn-Off Delay Time	t _{D(OFF)}	_	32.2	_	ns	$V_{DD} = 4V, V_{GEN} = 5V, I_{D} = 10A,$
Turn-On Rise Time	t _R	_	3.7	_	ns	$R_G = 1\Omega$, $R_L = 0.4\Omega$
Turn-Off Fall Time	t _F	_	11.6	_	ns	7
Body Diode Reverse Recovery Time	t _{RR}	_	20.55	_	ns	I _F = 10A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{rr}	_	4.5	_	nC	$I_F = 10A$, di/dt = $100A/\mu s$

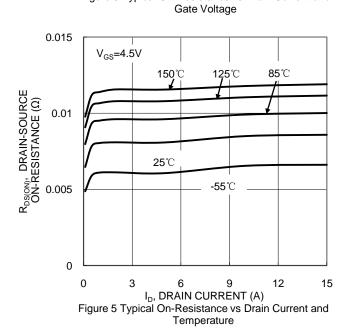
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad.

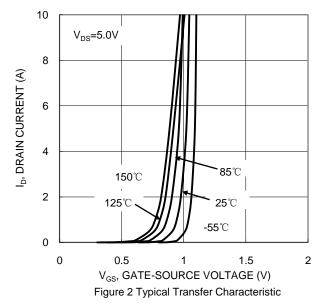
- 6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.

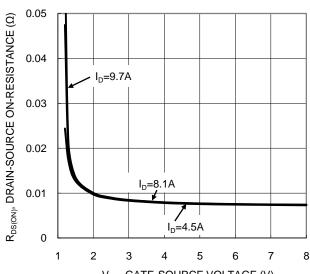












V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 4 Typical On-Resistance vs Drain Current and Gate Voltage

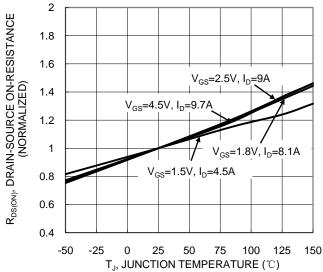
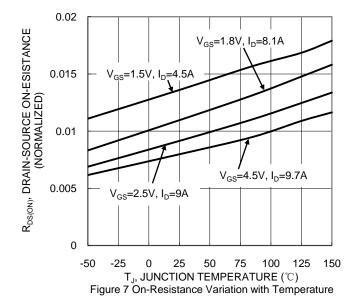
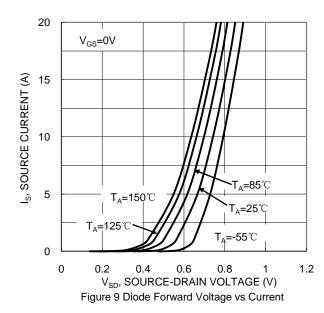
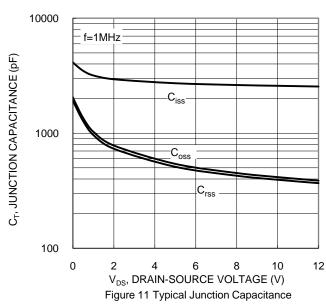


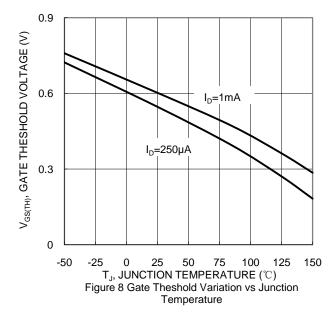
Figure 6 On-Resistance Variation with Temperature

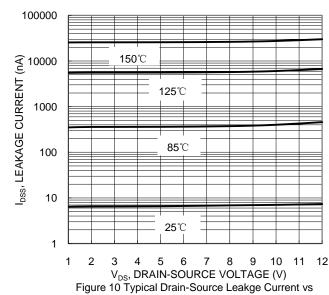


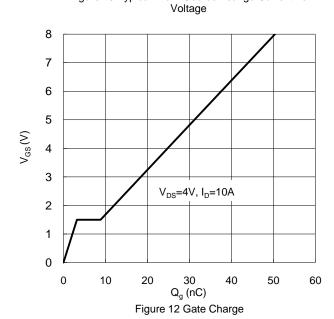




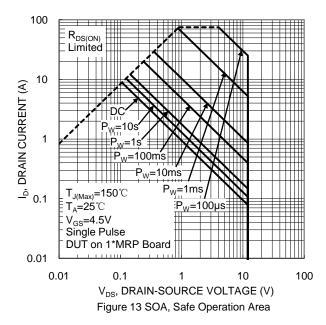


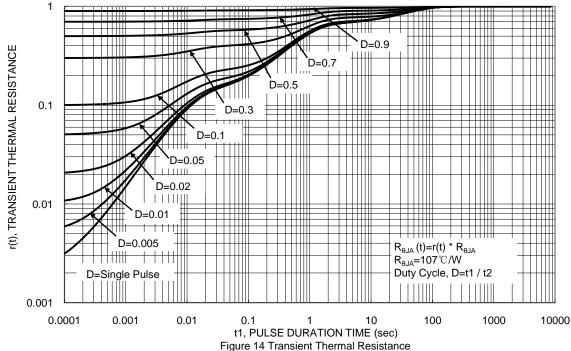








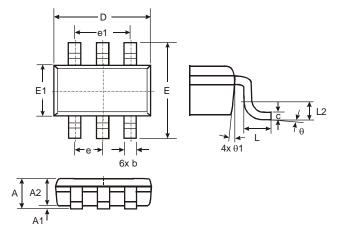






Package Outline Dimensions

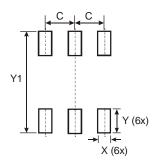
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TSOT26							
Dim	Min	Max	Тур				
Α	-	1.00	_				
A1	0.01	0.10	_				
A2	0.84	0.90	_				
D	-	_	2.90				
Е	1	_	2.80				
E1	-	_	1.60				
b	0.30	0.45	_				
С	0.12	0.20	_				
е	1	_	0.95				
e1	-	_	1.90				
L	0.30	0.50					
L2	_	_	0.25				
θ	0°	8°	4°				
θ1	4°	12°	_				
AII D	All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
Х	0.700
Y	1.000
Y1	3 199



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